



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Moon, et al

Serial No.: 10/025,144

Confirmation No.: 5051

Filed: December 18, 2001

For: Method and Apparatus for
Polishing Metal and
Dielectric Substrates

Group Art Unit: 2813

Examiner: Stephen W. Smoot

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TECHNOLOGY CENTER 2800

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on June <u>12</u> , 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.	
<u>06/12/2003</u> Date	<u>[Signature]</u> Signature

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RESPONSE TO OFFICE ACTION DATED MARCH 12, 2003

In response to the Office Action dated March 12, 2003, having a shortened statutory period for response set to expire on June 12, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. The Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/5999/KMT, for \$108.00 for 6 additional claims, and for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

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IN THE SPECIFICATION:

Please replace the title, with the following title: ✓

METHODS AND APPARATUS FOR POLISHING SUBSTRATES COMPRISING
CONDUCTIVE AND DIELECTRIC MATERIALS WITH REDUCED TOPOGRAPHICAL
DEFECTS

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